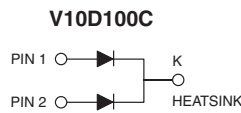
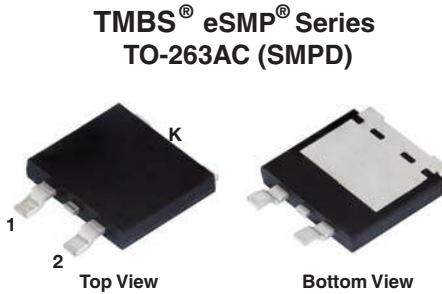


# Dual High-Voltage Trench MOS Barrier Schottky Rectifier

 Ultra Low  $V_F = 0.48 \text{ V}$  at  $I_F = 2.5 \text{ A}$ 


RoHS  
COMPLIANT  
HALOGEN  
FREE

## FEATURES

- Trench MOS Schottky technology generation 2
- Very low profile - typical height of 1.7 mm
- Ideal for automated placement
- Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available:
  - Automotive ordering code: base P/NHM3
- Material categorization: For definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

## TYPICAL APPLICATIONS

For use in high frequency DC/DC converters, switching power supplies, freewheeling diodes, OR-ing diode, and reverse battery protection in commercial, industrial, and automotive application.

## MECHANICAL DATA

**Case:** TO-263AC (SMPD)

Molding compound meets UL 94 V-0 flammability rating  
Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** Matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

**Polarity:** As marked

## PRIMARY CHARACTERISTICS

|   |                     |
|---|---------------------|
| $I_{F(AV)}$   | 2 x 5.0 A           |
| $V_{RRM}$   | 100 V               |
| $I_{FSM}$   | 100 A               |
| $V_F$ at $I_F = 5.0 \text{ A}$ ( $T_A = 125 \text{ °C}$ ) | 0.60 V              |
| $T_J$ max.  | 150 °C              |
| Package   | TO-263AC (SMPD)     |
| Diode variations  | Dual common cathode |

## MAXIMUM RATINGS ( $T_A = 25 \text{ °C}$ unless otherwise noted)

| PARAMETER   | SYMBOL         | V10D100C    | UNIT       |
|---|----------------|-------------|------------|
| Maximum repetitive peak reverse voltage   | $V_{RRM}$      | 100         | V          |
| Maximum average forward rectified current (fig. 1)                                | $I_{F(AV)}$    | per device  | 10         |
|   |                | per diode   | 5          |
| Maximum DC reverse voltage  | $V_{DC}$       | 160         | V          |
| Peak forward surge current 10 ms single half sine-wave superimposed on rated load | $I_{FSM}$      | 100         | A          |
| Voltage rate of change (rated $V_R$ )   | dV/dt          | 10 000      | V/ $\mu$ s |
| Operating junction and storage temperature range                                  | $T_J, T_{STG}$ | -40 to +150 | °C         |



| ELECTRICAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted) |                        |                         |                               |      |      |      |
|--|------------------------|-------------------------|-------------------------------|------|------|------|
| PARAMETER  | TEST CONDITIONS        |                         | SYMBOL                        | TYP. | MAX. | UNIT |
| Instantaneous forward voltage  | I <sub>F</sub> = 2.5 A | T <sub>A</sub> = 25 °C  | V <sub>F</sub> <sup>(1)</sup> | 0.55 | -    | V    |
|  | I <sub>F</sub> = 5.0 A |                         |                               | 0.67 | 0.75 |      |
|  | I <sub>F</sub> = 2.5 A | T <sub>A</sub> = 125 °C |                               | 0.48 | -    |      |
|  | I <sub>F</sub> = 5.0 A |                         |                               | 0.60 | 0.68 |      |
| Reverse current at rated V <sub>R</sub> per diode                          | V <sub>R</sub> = 70 V  | T <sub>A</sub> = 25 °C  | I <sub>R</sub> <sup>(2)</sup> | 2.3  | -    | μA   |
|  |                        | T <sub>A</sub> = 125 °C |                               | 2.3  | -    | mA   |
|  | V <sub>R</sub> = 100 V | T <sub>A</sub> = 25 °C  |                               | -    | 500  | μA   |
|  |                        | T <sub>A</sub> = 125 °C |                               | 7    | 20   | mA   |

**Notes**

- (1) Pulse test: 300 μs pulse width, 1 % duty cycle
- (2) Pulse test: Pulse width ≤ 5 ms

| THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted) |                  |                                    |      |
|---|------------------|------------------------------------|------|
| PARAMETER   | SYMBOL           | V10D100C                           | UNIT |
| Typical thermal resistance  | R <sub>θJC</sub> | per diode                          | 3.5  |
|   |                  | per device                         | 2.5  |
|   | per device       | R <sub>θJA</sub> <sup>(1)(2)</sup> | 48   |

**Notes**

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient: dP<sub>D</sub>/dT<sub>J</sub> < 1/R<sub>θJA</sub> - junction-to-mount
- (2) Free air, without heatsink

| ORDERING INFORMATION (Example) |                              |                 |              |               |                                    |
|--------------------------------|------------------------------|-----------------|--------------|---------------|------------------------------------|
| PACKAGE                        | PREFERRED P/N                | UNIT WEIGHT (g) | PACKAGE CODE | BASE QUANTITY | DELIVERY MODE                      |
| TO-263AC (SMPD)                | V10D100C-M3/I                | 0.55            | I            | 2000/reel     | 13" diameter plastic tape and reel |
| TO-263AC (SMPD)                | V10D100CHM3/I <sup>(1)</sup> | 0.55            | I            | 2000/reel     | 13" diameter plastic tape and reel |

**Note**

- (1) AEC-Q101 qualified

**RATINGS AND CHARACTERISTICS CURVES (T<sub>A</sub> = 25 °C unless otherwise noted)**

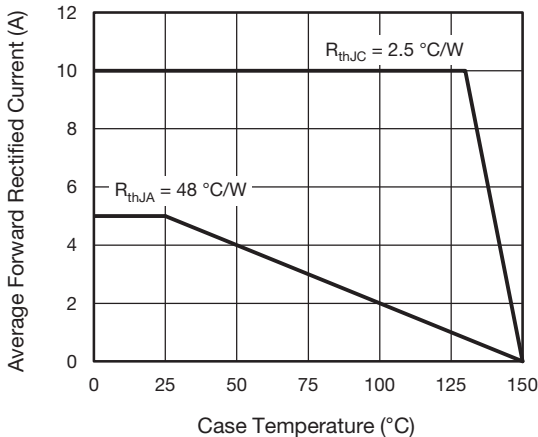


Fig. 1 - Maximum Forward Current Derating Curve

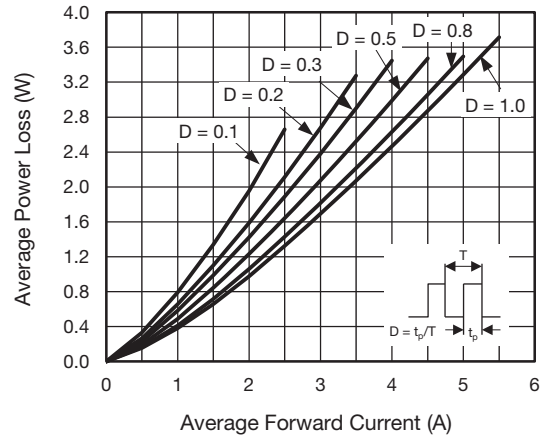


Fig. 2 - Average Power Loss Characteristics

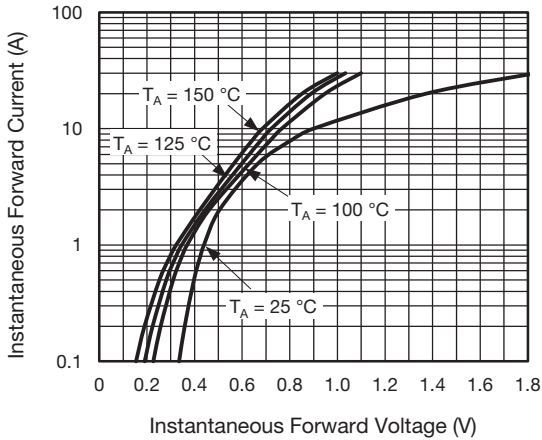


Fig. 3 - Typical Instantaneous Forward Characteristics

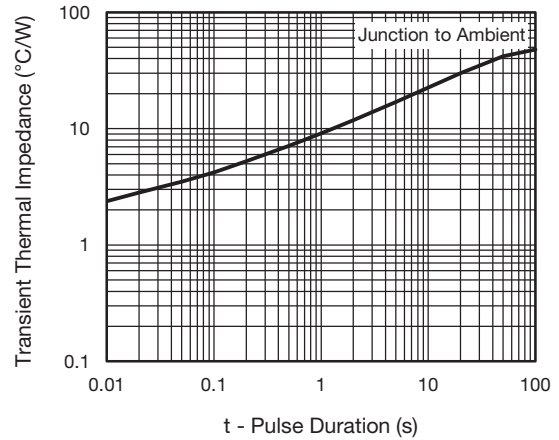


Fig. 6 - Typical Transient Thermal Impedance

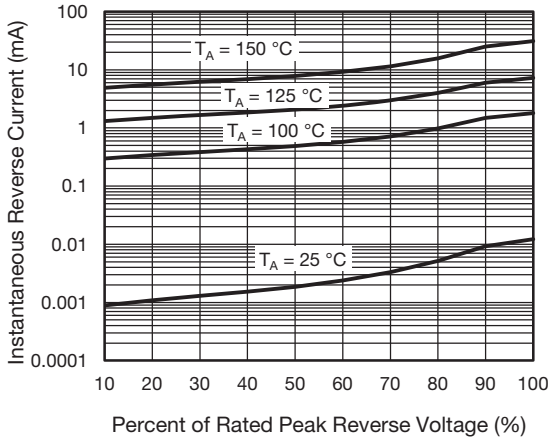


Fig. 4 - Typical Reverse Leakage Characteristics

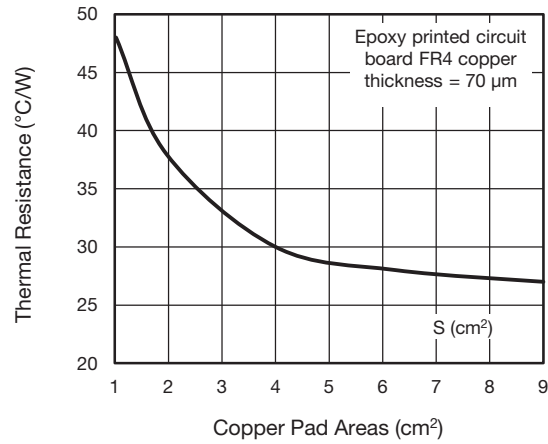


Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas

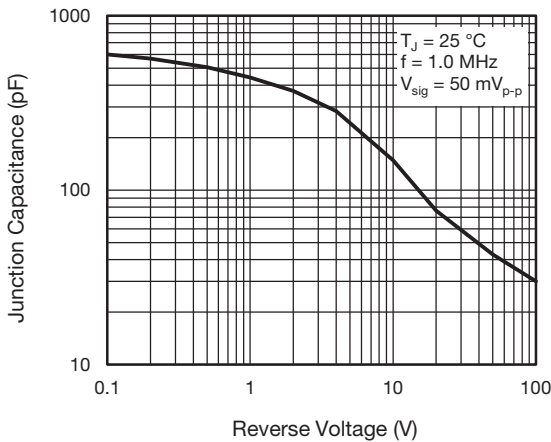
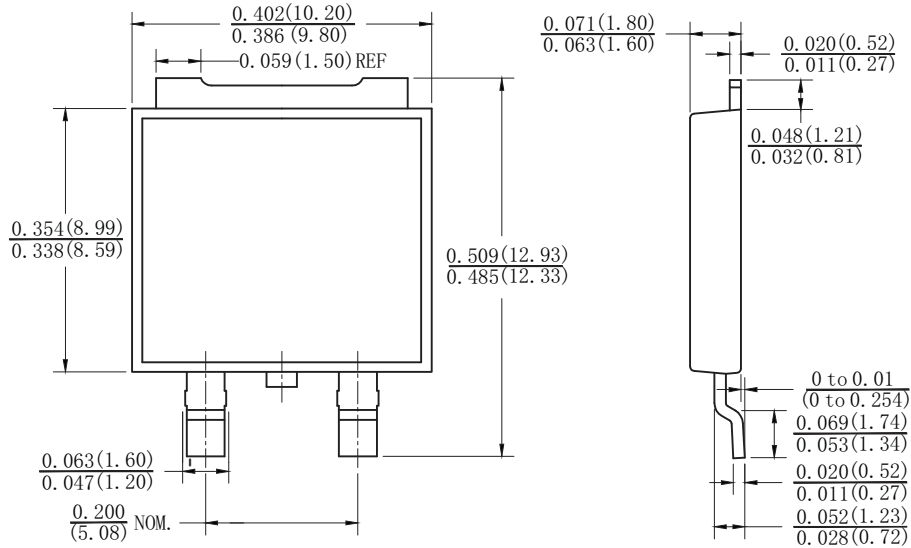


Fig. 5 - Typical Junction Capacitance

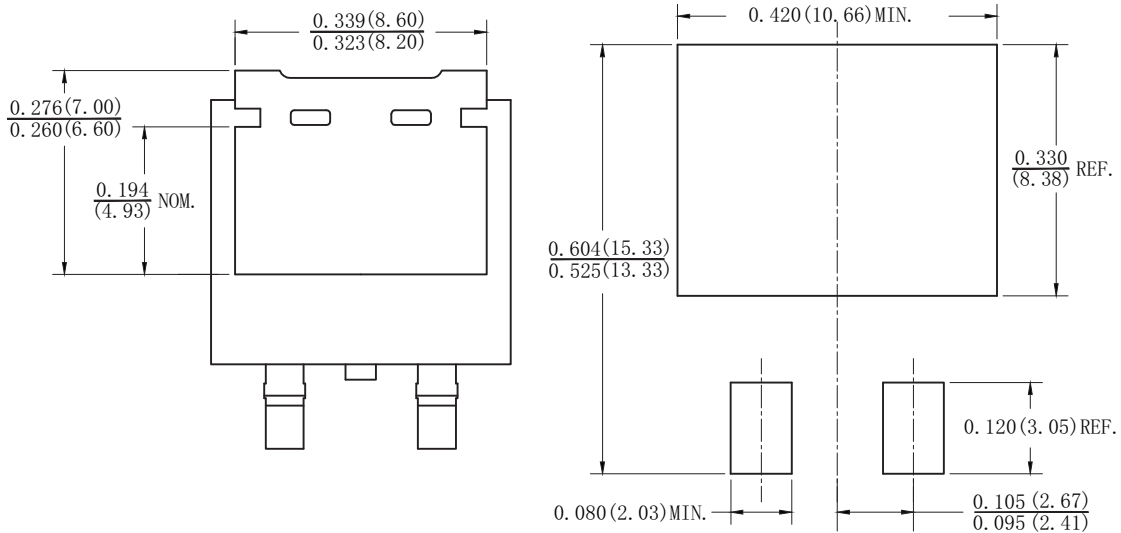


### PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

#### TO-263AC (SMPD)



#### Mounting Pad Layout





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